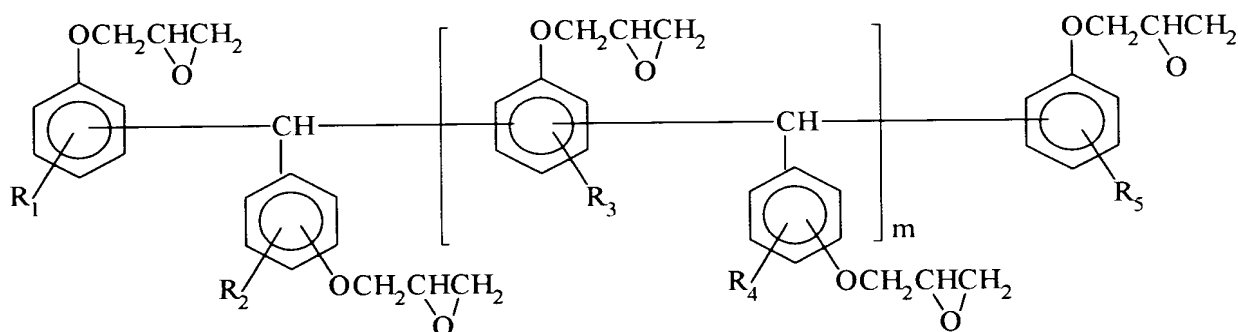


**WHAT IS CLAIMED IS:**

1. A process for producing a wafer with a resin layer comprising plural projected electrodes and a cured resin layer formed on a projected electrode mounting side of the wafer, comprising the steps of:

putting, on the projected electrode-mounting side of the wafer, a tablet comprising an epoxy resin composition, said epoxy resin composition comprising a curing agent and an epoxy resin represented by the general formula (1):

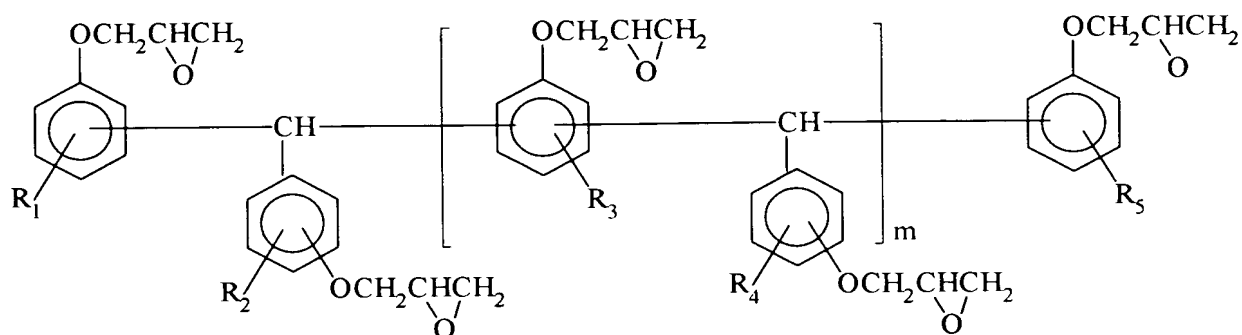


wherein each of  $R_1$  to  $R_5$  is a hydrogen atom and  $m$  is 0 or a positive number of 5 or less, wherein the amount of the tablet that is reduced by heating is less than 0.05% by weight, and

heating the tablet to be melt-cured, thereby forming the cured resin layer.

2. A process for producing a semiconductor device having substantially no bowing, said semiconductor device comprising an insulating substrate, a semiconductor element mounted on one side of the insulating substrate, and a cured product of an epoxy resin composition, the semiconductor element being incorporated in and sealed by the cured product, comprising the steps of:

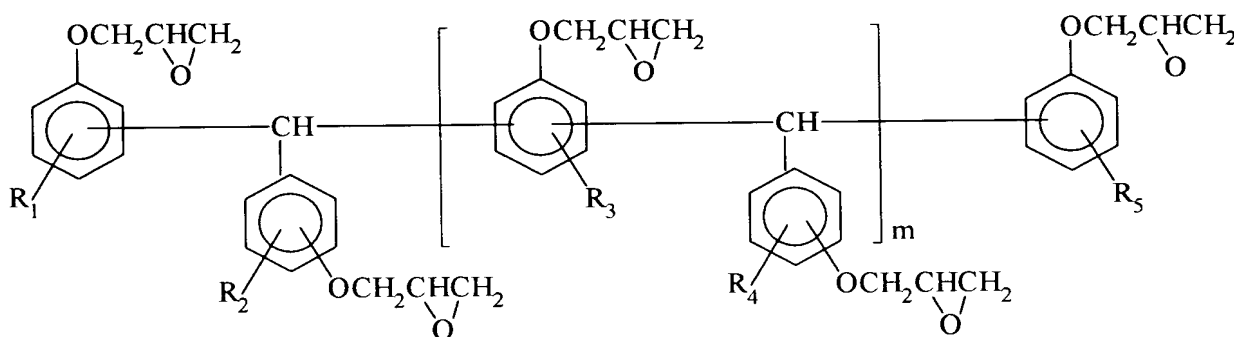
putting, on the semiconductor element, a tablet comprising an epoxy resin composition, said epoxy resin composition comprising a curing agent and an epoxy resin represented by the general formula (1):



wherein each of  $R_1$  to  $R_5$  is a hydrogen atom and  $m$  is 0 or a positive number of 5 or less, wherein the amount of the tablet that is reduced by heating is less than 0.05% by weight, and heating the tablet to be melt-cured, thereby forming the cured product.

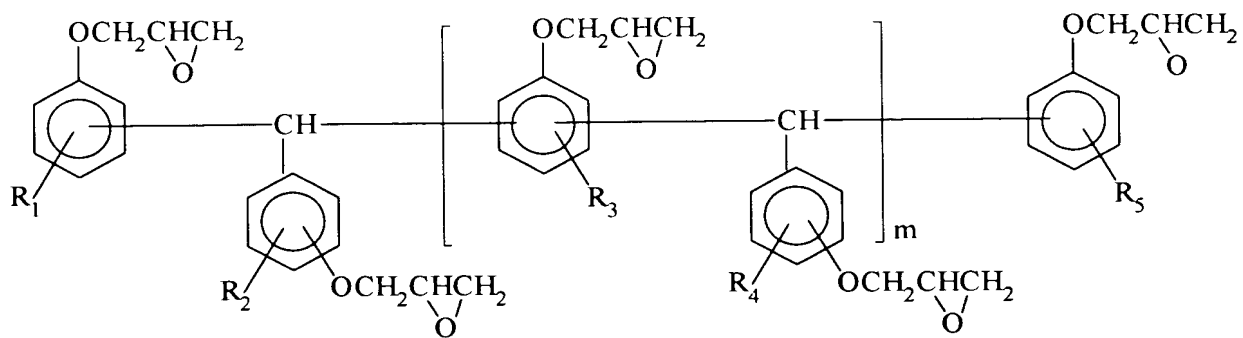
3. A process for producing a semiconductor device having substantially no bowing, said semiconductor device comprising an insulating substrate, a semiconductor element mounted on one side of the insulating substrate via a plural connecting electrodes, and a cured resin layer sealing a void between the insulating substrate and the semiconductor element, comprising the steps of:

heat-melting a tablet comprising an epoxy resin composition, said epoxy resin composition comprising a curing agent and an epoxy resin represented by the general formula (1):



wherein each of  $R_1$  to  $R_5$  is a hydrogen atom and  $m$  is 0 or a positive number of 5 or less, wherein the amount of the tablet that is reduced by heating is less than 0.05% by weight, and filling the void and curing the tablet, thereby forming the cured resin layer.





wherein each of  $R_1$  to  $R_5$  is a hydrogen atom and  $m$  is 0 or a positive number of 5 or less and a curing agent, wherein the amount of the tablet that is reduced by heating is less than 0.05% by weight.